

	Type	L #	Hits	Search Text	DBs
1	BRS	L11	393	257/671,701,675,712-718.ccl s. and (chip die IC) and ((lead adj frame) leadframe) and (heat adj (sink plate plug element spreader))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
2	BRS	L12	369	257/676,692,717,725,706.ccl s. and (chip die IC) and ((lead adj frame) leadframe) and (heat adj (sink plate plug element spreader))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
3	BRS	L13	259	257/666,669,672,674,690,696 .cccls. and (chip die IC) and ((lead adj frame) leadframe) and (heat adj (sink plate plug element spreader))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
4	BRS	L14	15	(chip die IC) and ((lead adj frame) leadframe) and (heat adj (sink plate plug element spreader)) and (metal adj block)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
5	BRS	L15	38	(chip die IC) and ((lead adj frame) leadframe) and (metal adj block)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
6	BRS	L16	2111	(chip die IC) and ((lead adj frame) leadframe) and (heat adj (sink plate plug element spreader))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB